

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2001-332864
(43)Date of publication of application : 30.11.2001

(51)Int.CI. H05K 3/46
H05K 3/18
H05K 3/38

(21)Application number : 2000-148352 (71)Applicant : SUMITOMO METAL ELECTRONICS
DEVICES INC

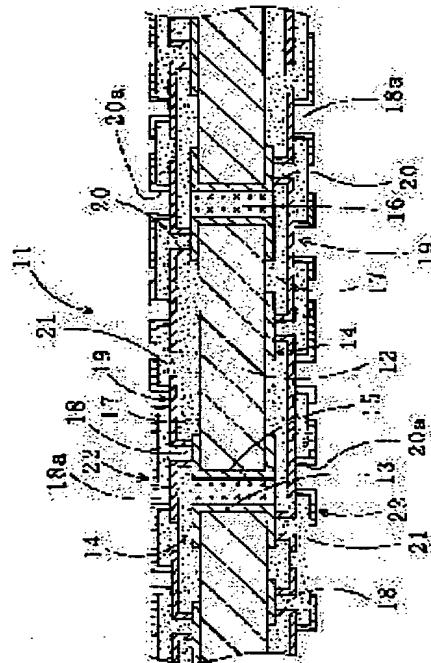
(22)Date of filing : 19.05.2000 (72)Inventor : TOMABECHI SHIGENAO

(54) MULTILAYER, WIRING BOARD FOR ELECTRONIC COMPONENT AND METHOD OF PRODUCTION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayer wiring board for electronic component and its producing method in which electric signal transmission performance is prevented from lowering by suppressing variation in the thickness of a copper electroless plating film and a copper electroplating film through optimization of surface state of an insulating resin layer, and the performance as a multilayer wiring board for electronic component is prevented from lowering by suppressing variation in the thickness of the insulating resin layer.

SOLUTION: In a multilayer wiring board 11 for electronic component having a copper electroless plating film 23 on insulating resin layers 17, 21 and its producing method, mean surface roughness of the insulating resin layers 17, 21 is set in the range of 1.0-3.0 μm and mean specific resistivity of the copper electroless plating film 23 is set in the range of 7-20 $\mu\text{ohm} \cdot \text{cm}$.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's

decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office